

28/4



IN THE UNITED STATES
PATENT AND TRADEMARK OFFICE

PATENT APPLICATION

INVENTORS:

Yinon Degani
Thomas Dixon Dudderar
Liguo Sun
Meng Zhao

CASE: 60-40-1-1

FIRST CLASS MAIL

These papers are being deposited
as FIRST CLASS MAIL with the
US POST OFFICE addressed to:
COMMISSIONER FOR PATENTS
Alexandria, VA 22313-1450
by [Signature]
date October 6, 2003

TITLE: STACKED MODULE PACKAGE

SERIAL NO. 09/964,009

GROUP ART UNIT 2814

FILING DATE 09/14/00

EXAMINER DiLinh P. Nguyen

**COMMISSIONER FOR PATENTS
ALEXANDRIA, VA 22313-1450**

RECEIVED
OCT 10 2003
TECHNICAL SERVICES

SIR:

In response to the Office action mailed 07/18/03 please amend the above
referenced application as follows:

In the claims:

Claims 1-22 canceled.

23. (currently amended) A The stacked MCM package of claim 22
wherein a the digital MCM is mounted on a digital MCM substrate and the
an RF MCM is mounted on an RF MCM substrate, the stacked MCM
package further comprising: